

**Amendments to the Claims:**

This listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

Claim 1 (currently amended): A method of fabricating a microelectronic package, comprising:

    providing a substrate having a first surface, an opposing second surface, and a plurality of lands disposed on said first surface;

    forming a through-hole extending from said substrate first surface to said substrate second surface;

    providing a microelectronic die having an active surface, a back surface, and a plurality of pads disposed on said active surface in a corresponding relationship to said plurality of substrate lands;

    electrically attaching said plurality of substrate lands to said plurality of corresponding microelectronic die pads with a plurality of conductive bumps;

    disposing an underfill material through said through-hole such that said underfill material is dispersed by capillary action between said microelectronic die active surface and said substrate first surface.

Claim 2 (original): The method of claim 1, wherein forming said through-hole comprises forming said through-hole by at least one of the methods consisting of drilling, laser ablation, and etching.

Claim 3 (original): The method of claim 1, wherein disposing said underfill material comprises positioning an underfill material dispensing device proximate said through-hole and injecting said underfill material into said through-hole.

Claim 4 (original): The method of claim 1, wherein positioning said underfill material dispensing device proximate said through-hole comprises positioning a dispensing needle proximate said through-hole.

Claim 5 (original): The method of claim 1, wherein disposing said underfill material comprises disposing an epoxy material.

Claim 6 (original): The method of claim 1, further including curing said underfill material.

Claim 7 (currently amended): A method of fabricating a microelectronic package, comprising:

providing a substrate having a first surface, an opposing second surface, and a plurality of lands disposed on said first surface;

forming a through-hole extending from said substrate first surface to said substrate second surface;

providing a microelectronic die having an active surface, a back surface, and a plurality

of pads disposed on said active surface in a corresponding relationship to said plurality of substrate lands;

electrically attaching said plurality of substrate lands to said plurality of corresponding microelectronic die pads with a plurality of conductive bumps;

positioning said microelectronic die and said substrate such that said microelectronic die is gravitationally below said substrate; and

disposing an underfill material through said through-hole such that said underfill material is dispersed by capillary action between said microelectronic die active surface and said substrate first surface.

Claim 8 (original): The method of claim 7, wherein forming said through-hole comprises forming said through-hole by at least one of the methods consisting of drilling, laser ablation, and etching.

Claim 9 (original): The method of claim 7, wherein disposing said underfill material comprises positioning an underfill material dispensing device proximate said through-hole and injecting said underfill material into said through-hole.

Claim 10 (original): The method of claim 9, wherein positioning said underfill material dispensing device proximate said through-hole comprises positioning a dispensing needle proximate said through-hole.

Claim 11 (original): The method of claim 7, wherein disposing said underfill material comprises disposing an epoxy material.

Claim 12 (original): The method of claim 7, further including curing said underfill material.

Claim 13 (currently amended): A method of fabricating a microelectronic package, comprising:

providing a substrate having a first surface, an opposing second surface, a plurality of lands disposed on said first surface, and at least one wirebond land on said first surface;

forming a through-hole extending from said substrate first surface to said substrate second surface;

providing a microelectronic die having an active surface, a back surface, and a plurality of pads disposed on said active surface in a corresponding relationship to said plurality of substrate lands;

electrically attaching said plurality of substrate lands to said plurality of corresponding microelectronic die pads with a plurality of conductive bumps;

disposing an underfill material through said through-hole such that said underfill material is dispersed by capillary action between said microelectronic die active surface and said substrate first surface;

providing a second microelectronic die having an active surface, a back surface, and at least one wirebond pad disposed on said active surface;

attaching said second microelectronic die back surface to said microelectronic die back surface; and

attaching at least one wirebond between said at least one substrate wirebond land and said second microelectronic die wirebond pad.

Claim 14 (original): The method of claim 13, wherein forming said through-hole comprises forming said through-hole by at least one of the methods consisting of drilling, laser ablation, and etching.

Claim 15 (original): The method of claim 13, wherein disposing said underfill material comprises positioning an underfill material dispensing device proximate said through-hole and injecting said underfill material into said through-hole.

Claim 16 (original): The method of claim 15, wherein positioning said underfill material dispensing device proximate said through-hole comprises positioning a dispensing needle proximate said through-hole.

Claim 17 (original): The method of claim 13, wherein disposing said underfill material comprises disposing an epoxy material.

Claim 18 (original): The method of claim 13, further including curing said underfill material.

Claim 19 (original): The method of claim 13, wherein said attaching said second microelectronic die back surface to said microelectronic die back surface comprises disposing a layer of adhesive therebetween.

Claim 20 (original): The method of claim 13, wherein further including positioning said microelectronic die and said substrate such that said microelectronic die is gravitationally below said substrate prior to disposing said underfill material.